

## IN THE CLAIMS

Claims 1-26 have been previously canceled, without prejudice, as being drawn to a non-elected invention.

Claims 27-53, 55-58, 60-63, 65-67, and 68-75 have been previously canceled, without prejudice.

Please amend claims 54, 59, and 64.

Please enter the following pending claims, including claims 54, 59, 64, and the renumbered claims 76-87:

1. - 53. (Canceled)

54. (Currently Amended) A polish pad comprising:

a first set of grooves disposed in a first area, said first set of grooves having a first depth; and

a second set of grooves disposed in a second area, said second set of grooves having a second depth, wherein said first set of grooves does not intersect said second set of grooves and wherein said first depth is smaller than said second depth to reduce polish rate in said first area.

55. - 58. (Canceled)

59. (Currently Amended) A polish pad comprising:

a first set of grooves disposed in a first area, said first set of grooves having a first width; and

a second set of grooves disposed in a second area, said second set of grooves having a second width, wherein said first set of grooves does not intersect said second set of grooves and wherein said first width is smaller than said second width to reduce polish rate in said first area.

60. - 63. (Canceled)

64. (Currently Amended) A polish pad comprising:

a first set of grooves disposed in a first area, said first set of grooves having a first density; and

a second set of grooves disposed in a second area, said second set of grooves having a second density, wherein said first set of grooves does not intersect said second set of grooves and wherein said first density is smaller than said second density to reduce polish rate in said first area.

65. - 75. (Canceled)

76. (Previously Presented) The polish pad of claim 54 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

77. (Previously Presented) The polish pad of claim 54 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

78. (Previously Presented) The polish pad of claim 54 wherein said first area is disposed in a center of said polish pad.

79. (Previously Presented) The polish pad of claim 54 wherein said first area is disposed at edges of said polish pad.

80. (Previously Presented) The polish pad of claim 59 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

81. (Previously Presented) The polish pad of claim 59 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

82. (Previously Presented) The polish pad of claim 59 wherein said first area is disposed in a center of said polish pad.

83. (Previously Presented) The polish pad of claim 59 wherein said first area is disposed at edges of said polish pad.

84. (Previously Presented) The polish pad of claim 64 wherein said first area corresponds to a center of a wafer to be polished on said polish pad.

85. (Previously Presented) The polish pad of claim 64 wherein said first area corresponds to edges of a wafer to be polished on said polish pad.

86. (Previously Presented) The polish pad of claim 64 wherein said first area is disposed in a center of said polish pad.

87. (Previously Presented) The polish pad of claim 64 wherein said first area is disposed at edges of said polish pad.